	Type	Hits	Search Text	DBs
1	BRS	13	("5924622"|"6333638"|"4744140"|"569050 4"|"5887344"|"5895554"|"5930889"|"6384 360"|"5829988"|"6561836"|"5805427"|"58 10609"|"5987742").PN.	USPAT
2	BRS	13	("5924622"|"6333638"|"4744140"|"569050 4"|"5887344"|"5895554"|"5930889"|"6384 360"|"5829988"|"6561836"|"5805427"|"58 10609"|"5987742").PN.	US-PGPUB; USPAT; USOCR
3	BRS	126	"36217"	US-PGPUB; USPAT; USOCR
4	BRS	6	"re36217"	US-PGPUB; USPAT; USOCR
5	IS&R	4	(("5987742") or ("5690504")).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB
6	IS&R	5801	(324/758,761,765).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB
7	IS&R	1842	(324/758,761,).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB
8	IS&R	2	("20030094706").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB
9	IS&R	160	(439/41,940).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB
10	IS&R	0	("9and@ad<20010830").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB

	Type	Hits	Search Text	DBs
11	BRS	88	S9 and @ad<"20010830"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB
12	BRS	11	S9 and @rlad<"20010830"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB
13	BRS	88	S11 S12	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB
14	BRS	0	439/46,64,79,84	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB
15	IS&R	1710	(439/46,64,79,84).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB
16	BRS	1197	S15 and @ad<"20010830"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB
17	BRS	200	S15 and @rlad<"20010830"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB
18	BRS	1216	S16 S17	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB
19	BRS	1212	S18 not S9	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB
20	BRS	171	(chip or die or chips or (semiconductor near2 substrate)) and S19	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB

	Type	Hits	Search Text	DBs
21	BRS	110000	(vacuum or suction or pick or lift$4) near15 (chip or chips or die or substrate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB
22	BRS	5292	(pcb or printed adj circuit) and S21	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB
23	BRS	4550	(vacuum or suction or pick or lift$4) near15 (chip or chips or die or substrate) near15 (guide or aligment or aligning or pin or pins)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB
24	BRS	355	(pcb or printed adj circuit) and S23	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB
25	BRS	230	S24 and @ad<"20010830"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB
26	BRS	99	S24 and @rlad<"20010830"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB
27	BRS	261	S25 S26	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB
28	IS&R	6	(("6693674") or ("6384360") or ("4744140")).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB
29	IS&R	0	(" (guidenear2(pinorpins))near15(mechanicalnear2selfnear2lock$3)").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB
30	BRS	0	(guide near2 (pin or pins)) near15 (mechanical near2 self near2 lock$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB

Type	Hits	Search Text	DBs
31 BRS	2	(pin or pins) near15 (mechanical near2 self near2 lock$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB
32 BRS	1687	(pin or pins) near15 (self near2 lock$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB
33 BRS	21	(guide near2 (pin or pins)) near15 (self near2 lock$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB